

ABSTRACT

The present invention is a two-phase liquid cooling system that cools a plurality of electronic components connected in parallel. A pump delivers a cooling fluid, as a liquid, to a supply manifold wherein it splits into distinct branch lines. Preferably, the branch lines feed coolant to individual spray modules. The liquid coolant removes heat from the components to be cooled. The resulting liquid and vapor mixture exit the spray modules via a plurality of return branches. Each individual return branch feeds into a return manifold at an acute angle. The angular transitions between the return branches and the return manifold provides low manifold losses and a more efficient system.